

DELKIN DEVICES®

M.2

SATA III Industrial Solid State Drive

Engineering Specification

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Revision: B



Product Overview

- **Capacity**
 - 32GB up to 512GB
- **SATA Interface**
 - SATA Revision 3.2
 - SATA 1.5Gbps, 3Gbps, and 6Gbps interface
- **Flash Interface**
 - Flash type: 3D TLC
- **Performance**
 - Read: up to 550 MB/s
 - Write: up to 490 MB/s
- **Power Consumption**^{Note1}
 - Active mode: < 1,520 mW
 - Idle mode: < 325 mW
- **TBW (Terabytes Written)**^{Note2}
 - 425 TBW for 512GB
- **MTBF**
 - More than 2,000,000 hours
- **Features**
 - Static and Dynamic Wear Leveling
 - Bad Block Management
 - TRIM
 - NCQ
 - SMART
 - Over-Provisioning
 - Firmware Update Capability
- **Low Power Management**
 - DIPM/HIPM Mode
 - DEVSLP Mode (Optional)
- **Temperature Range**
 - Operation: -40°C ~ 85°C
 - Storage: -40°C ~ 85°C
- **RoHS compliant**

Notes:

1. Please see “4.2 Power Consumption” for details.
2. Please see “TBW (Terabytes Written)” in Chapter 2” for details.

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1. INTRODUCTION

1.1. General Description

Delkin Devices' M.2 2242 Industrial 3D TLC Solid State Drive (SSD) delivers all the advantages of flash disk technology with the performance of the Serial ATA III interface and is fully compliant with the standard Next Generation Form Factor (NGFF) or M.2. Delkin's SSD draws significantly less power compared to traditional hard drives and is ideal for embedded applications. The drive is available in capacities from 32GB to 512GB and can reach speeds up to 550 MB/s read and 490MB/s write (measured by Crystal DiskMark v5.0).

1.2. Product Block Diagram

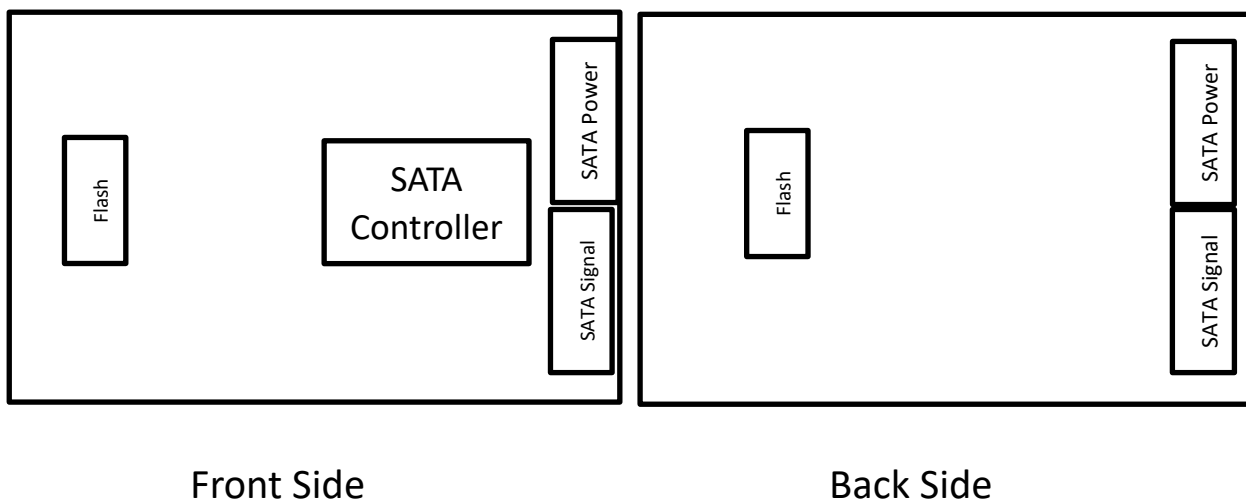


Figure 1-1 Product Block Diagram

1.3. Flash Management

1.3.1. Error Correction Code (ECC)

Flash memory cells will deteriorate with use, which might generate random bit errors in the stored data. Thus, Delkin's M.2 2242 SSD utilizes a sophisticated LDPC (Low Density Parity Check) ECC algorithm, which can detect and correct errors occur during read process, ensure data been read correctly, as well as protect data from corruption.

1.3.2. Wear Leveling

NAND flash devices can only undergo a limited number of program/erase cycles, and in most cases, the flash media are not used evenly. If some areas are updated more frequently than others, the lifetime of the device would be reduced significantly. Thus, Wear Leveling is applied to extend the lifespan of NAND flash by evenly distributing write and erase cycles across the media.

Delkin utilizes advanced Wear Leveling algorithms, which can efficiently distribute flash usage through the whole flash media area. Moreover, by implementing both dynamic and static Wear Leveling algorithms, the life expectancy of the NAND flash is greatly improved.

1.3.3. Bad Block Management

Bad blocks are blocks that include one or more invalid bits, and their reliability is not guaranteed. Blocks that are identified and marked as bad by the manufacturer are referred to as “Initial Bad Blocks”. Bad blocks that are developed during usage of the flash are named “Later Bad Blocks”. Delkin implements an efficient bad block management algorithm to detect the factory-produced bad blocks and manages any bad blocks that appear with use. This practice further prevents data being stored into bad blocks and improves data reliability.

1.3.4. TRIM

TRIM is a feature which helps improve the read/write performance and speed of solid-state drives (SSD). Unlike hard disk drives (HDD), SSDs are not able to overwrite existing data, so the available space gradually becomes smaller with each use. With the TRIM command, the operating system can inform the SSD which blocks of data are no longer in use and can be removed permanently. Thus, the SSD will perform an erase action, which prevents unused data from occupying blocks.

1.3.5. SMART

SMART, an acronym for Self-Monitoring, Analysis and Reporting Technology, is an open standard that allows a drive to automatically detect its health and report potential failures. When a failure is recorded by SMART, users can choose to replace the drive to prevent unexpected outage or data loss. Moreover, SMART can inform users of impending failures while there is still time to perform proactive actions, such as copy data to another device.

1.3.6. Over-Provisioning

Over Provisioning refers to the inclusion of extra NAND capacity in a SSD, which is not visible or usable by users. With Over Provisioning, the performance and IOPS (Input/Output Operations per

Second) are improved by providing the controller additional space to manage P/E cycles, which enhances the reliability and endurance as well. Moreover, the write amplification of the SSD becomes lower when the controller writes data to the flash.

1.3.7. Firmware Upgrades

Firmware can be considered as a set of instructions on how the device communicates with the host. Firmware can be upgraded when new features are added, compatibility issues are fixed, or read/write performance gets improved, as controlled by the user. It is possible to update firmware in the field, however, there are important factors to consider before attempting a firmware upgrade. Contact Delkin technical support for more information.

1.4. Low Power Management

1.4.1. DIPM/HIPM Mode

SATA interfaces contain two low power management states for power saving: Partial and Slumber modes. In Partial mode, the device must resume full operation within 10 microseconds, whereas in Slumber mode, the device has 10 milliseconds to become fully operational. SATA interfaces allow low power modes to be initiated by Host (HIPM, Host Initiated Power Management) or Device (DIPM, Device Initiated Power Management). As for HIPM, Partial or Slumber mode can be invoked directly by the software. For DIPM, the device will send requests to enter Partial or Slumber mode.

1.5. DEVSLP Mode (Optional)

With the increasing need of aggressive power/battery life, SATA interfaces include a new feature, Device Sleep (DEVSLP) mode, which helps further reduce the power consumption of the device. DEVSLP enables the device to completely power down the device PHY and other sub-systems, making the device reach a new level of lower power operation. The DEVSLP does not specify the exact power level a device can achieve in the DEVSLP mode, but the power usage can be dropped down to 5mW or less.

1.6. Power Loss Protection: Flushing Mechanism (Optional)

Power Loss Protection is a mechanism to prevent data loss during unexpected power failures. DRAM is volatile memory and frequently used as temporary cache or buffer between the controller and the NAND flash to improve SSD performance. However, one major concern of the DRAM is that data could be lost in the event of a power failure. Accordingly, the Delkin SATA controller applies the

GuaranteedFlush technology, which requests the controller to transfer data to the cache. Only when the data is fully committed to the NAND flash will the controller send acknowledgement (ACK) to the host. Such implementation can prevent false-positive performance and the risk of power cycling issues.

Additionally, it is critical for a controller to shorten the time the in-flight data stays in the cache. Thus, Delkin's controller applies an algorithm to reduce the amount of data residing in the cache to provide better performance. This SmartCacheFlush technology allows incoming data to have only a brief "pit stop" in the cache and then move straight to the NAND flash. If the flash is jammed due to particular file sizes (such as random 4KB data), the cache will be treated as an "organizer", consolidating incoming data into groups before written into the flash to improve write amplification. In summary, with this advanced Flush Mechanism, Delkin's controller provides the reliability and data protection required by today's applications and hosts.

1.7. Advanced Device Security Features

1.7.1. Secure Erase

Secure Erase is a standard ATA command and will write "0xFF" to all cells, to fully wipe all the data on hard drives and SSDs. When this command is issued, the SSD controller will erase its storage blocks and return to its factory default settings.

1.7.2. Write Protect

When a SSD contains too many bad blocks and data is continuously written in, then the SSD may no longer be usable. Thus, Write Protect is a mechanism to prevent data from being written in and protect the accuracy of data that are already stored in the SSD.

1.8. SSD Lifetime Management

1.8.1. Terabytes Written (TBW)

TBW (Terabytes Written) is a measurement of SSDs' expected lifespan, which represents the amount of data written to the device. To calculate the TBW of a SSD, the following equation is applied:

$$TBW = [(NAND\ Endurance) \times (SSD\ Capacity) \times (WLE)] / WAF$$

NAND Endurance: NAND endurance refers to the P/E (Program/Erase) cycle rating of NAND flash, per the manufacturer's specification.

SSD Capacity: The SSD capacity is the specific capacity in total of a SSD.

WLE: Wear Leveling Efficiency (WLE) represents the ratio of the average amount of erases on all

the blocks to the erases on any block at maximum.

WAF: Write Amplification Factor (WAF) is a numerical value representing the ratio between the amount of data that a SSD controller writes to the flash and the amount of data that the host's flash controller writes. A better WAF, which is near 1, guarantees better endurance and lower frequency of data written to flash memory.

1.8.2. Thermal Monitor (Optional)

Thermal monitors are devices for measuring temperature, and can be found in SSDs in order to issue warnings when SSDs go beyond a certain temperature. The higher temperature the thermal monitor detects, the more power the SSD consumes, causing the SSD to age quickly. Hence, the processing speed of a SSD should be under control to prevent temperature from exceeding a certain range.

1.9. An Adaptive Approach to Performance Tuning

1.9.1. Throughput

Based on the available space of the disk, Delkin SSD controller will regulate the read/write speed and manage the throughput performance. When significant free space remains, the firmware will continuously perform read/write activity. At this stage, there is still no need to implement garbage collection to allocate and release memory, which will accelerate read/write processing to improve the performance. However, when free space is used up, the controller will slow down the read/write processing, and implement garbage collection to release memory blocks. Hence, read/write performance will become slower.

1.9.2. Predict & Fetch

Normally, when the host tries to read data from the SSD, the SSD will only perform one read action after receiving one command. However, Delkin's controller applies **Predict & Fetch** to improve the read speed. When the host issues sequential read commands to the SSD, the SSD will automatically expect that the following will also be read commands. Thus, before receiving the next command, flash has already prepared the data. Accordingly, this accelerates the data processing

time, and the host does not need to wait as long to receive data.

2. PRODUCT SPECIFICATIONS

- **Capacity**
 - From 32GB up to 512GB

- **Electrical/Physical Interface**
 - SATA Interface
 - ◆ Compliant with SATA Revision 3.2
 - ◆ Compatible with SATA 1.5Gbps, 3Gbps and 6Gbps interface
 - ◆ Supports power management
 - ◆ Supports expanded register for SATA protocol 48 bit addressing mode

- **ECC Scheme**
 - LDPC (Low Density Parity Check) ECC Algorithm

- **Supports SMART and TRIM commands**

- **Performance**

Capacity	Sequential Performance	
	CrystalDiskMark	
	Read (MB/s)	Write (MB/s)
32GB	295	125
64GB	550	255
128GB	550	450
256GB	550	490
512GB	550	490

Notes:

1. Performance measured with CrystalDiskMark v5.0 x 64 with SATA 6Gbps host.
2. Performance may vary with host platform.
3. Table above is for reference only.

- **Endurance - TBW (Terabytes Written)**

Capacity	TBW
32GB	17
64GB	42
128GB	75
256GB	180
512GB	425

NOTES:

1. Many factors affect drive endurance / TBW, including flash configuration, SDR configuration, host platform, usage model, write amplification factor, etc. The figures above are estimates and are not guarantees. The test followed JEDEC219A client endurance workload

- **Part Numbers**

**M.2 2242 Industrial TLC SSD
Industrial Temperature (-40 to 85°C)**

Capacity	Part Number
32GB	MB32FQQFZ-42000-2
64GB	MB64FQQFZ-42000-2
128GB	MB1HFRCFZ-42000-2
256GB	MB2HFQXFZ-42000-2
512GB	MB5HFRAFZ-42000-2

3. ENVIRONMENTAL SPECIFICATIONS

3.1. Environmental Conditions

3.1.1. Temperature and Humidity

- Temperature:
 - ◆ Storage: -40°C to 85°C
 - ◆ Operational: -40°C to 85°C
- Humidity:
 - ◆ RH 95% under 55°C (operational)

3.1.2. Shock & Vibration

- Shock Specification
 - ◆ 1500G, 0.5ms duration
- Vibration Specification
 - ◆ 20Hz ~80Hz/1.52mm displacement, 80Hz~2000Hz / 20G Acceleration, 3 axes

3.1.3. Electrostatic Discharge (ESD)

- +/- 4KV

3.1.4. EMI Compliance

- FCC: CISPR22
- CE: EN55022
- BSMI 13438

3.2. MTBF

MTBF, an acronym for Mean Time Between Failures, is a measure of a device's reliability. Its value represents the average time between a repair and the next failure. The measure is typically in units of hours. The higher the MTBF value, the higher the reliability of the device. The predicted result of Delkin's M.2 SSD is more than 2,000,000 hours at 0°C.

3.3. Certification & Compliance

- RoHS
- SATA III (SATA Rev. 3.0)
- Up to ATA/ATAPI-8 (Including S.M.A.R.T)

WARNING: This product may contain chemicals known to the State of California to cause cancer, birth defects, or other reproductive harm. For more information go to www.p65warnings.ca.gov.

4. ELECTRICAL SPECIFICATIONS

4.1. Supply Voltage

Table 4-1 Supply Voltage

Parameter	Rating
Operating Voltage	3.3V ± 5%

4.2. Power Consumption

Table 4-2 Power Consumption

Capacity	Read	Write	Partial	Slumber	Idle
32GB	1,100	1,000	15	10	300
64GB	1,215	1,020	15	10	300
128GB	1,300	1,350	15	10	300
256GB	1,360	1,440	20	15	325
512GB	1,470	1,520	22	15	325

Unit: mW

NOTES:

1. The average value of power consumption is achieved based on 100% conversion efficiency.
2. The measured power voltage is 3.3V.
3. Sequential R/W is measured while testing 4000MB sequential R/W 5 times by CrystalDiskMark.
4. Power Consumption may differ according to flash configuration, SDR configuration, and host platform.

5. INTERFACE

5.1. Pin Assignment and Descriptions

Table 5-1 defines the signal assignment of the internal NGFF connector for SSD usage, described in the PCI Express M.2 Specification, version 1.0 of the PCI-SIG.

Table 5-1 Pin Assignment and Descriptions for M.2

Pin #	SATA Pin	Description
1	CONFIG_3	Ground
2	3.3V	Supply pin
3	GND	Ground
4	3.3V	Supply pin
5	N/C	No Connect
6	N/C	No Connect
7	N/C	No Connect
8	N/C	No Connect
9	N/C or GND ^{Note}	No Connect or Ground
10	DAS/DSS# (O) (OD)	Status indicators via LED devices that will be provided by the system Active Low. A pulled-up LED with series current limiting resistor should allow for 9mA when On.
11	N/C	No Connect
12	Module Key	
13	Module Key	
14	Module Key	
15	Module Key	
16	Module Key	
17	Module Key	
18	Module Key	
19	Module Key	
20	N/C	No Connect
21	CONFIG_0	Ground
22	N/C	No Connect
23	N/C	No Connect
24	N/C	No Connect
25	N/C	No Connect
26	N/C	No Connect
27	GND	Ground

Pin #	SATA Pin	Description
28	N/C	No Connect
29	N/C	No Connect
30	N/C	No Connect
31	N/C	No Connect
32	N/C	No Connect
33	GND	Ground
34	N/C	No Connect
35	N/C	No Connect
36	N/C	No Connect
37	N/C	No Connect
38	DEVSLP (I) (0/3.3V)	Device Sleep, Input. When driven high the host is informing the SSD to enter a low power state
39	GND	Ground
40	N/C	No Connect
41	SATA-B+	SATA differential signals in the SATA specification
42	N/C	No Connect
43	SATA-B-	SATA differential signals in the SATA specification
44	N/C	No Connect
45	GND	Ground
46	N/C	No Connect
47	SATA-A-	SATA differential signals in the SATA specification
48	N/C	No Connect
49	SATA-A+	SATA differential signals in the SATA specification
50	N/C	No Connect
51	GND	Ground
52	N/C	No Connect
53	N/C	No Connect
54	N/C	No Connect
55	N/C	No Connect
56	Reserved for MFG Data	No Connect
57	GND	Ground
58	Reserved for MFG Clock	No Connect
59	Module Key	

Pin #	SATA Pin	Description
60	Module Key	
61	Module Key	
62	Module Key	
63	Module Key	
64	Module Key	
65	Module Key	
66	Module Key	
67	N/C	No Connect
68	SUSCLK (I) (0/3.3V)	No Connect
69	CONFIG_1	Ground
70	3.3V	Supply pin
71	GND	Ground
72	3.3V	Supply pin
73	GND	Ground
74	3.3V	Supply pin
75	CONFIG_2	Ground

NOTE: N/C for Socket 2, and GND for Socket 3.

6. SUPPORTED COMMANDS

6.1. ATA Command List

The following ATA command list table is followed by ATA8-ACS4 SPEC.

Table 6-1 ATA Command List

Op Code	Description	Op Code	Description	
00h	NOP	C9h	Read DMA without Retry	
06h	Data Set Management	CAh	Write DMA	
10h-1Fh	Recalibrate	CBh	Write DMA without Retry	
20h	Read Sectors	CEh	Write Multiple FUA EXT	
21h	Read Sectors without Retry	E0h	Standby Immediate	
24h	Read Sectors EXT	E1h	Idle Immediate	
25h	Read DMA EXT	E2h	Standby	
27h	Read Native Max Address EXT	E3h	Idle	
29h	Read Multiple EXT	E4h	Read Buffer	
2Fh	Read Log EXT	E5h	Check Power Mode	
30h	Write Sectors	E6h	Sleep	
31h	Write Sectors without Retry	E7h	Flush Cache	
34h	Write Sectors EXT	E8h	Write Buffer	
35h	Write DMA EXT	E9h	READ BUFFER DMA	
37h	Set Native Max Address EXT	EAh	Flush Cache EXT	
38h	CFA Write Sectors Without Erase	EBh	Write Buffer DMA	
39h	Write Multiple EXT	ECh	Identify Device	
3Dh	Write DMA FUA EXT	EFh	Set Features	
3Fh	Write Long EXT	EFh	02h	Enable volatile write cache
40h	Read Verify Sectors	EFh	03h	Set transfer mode
41h	Read Verify Sectors without Retry	EFh	05h	Enable the APM feature set
42h	Read Verify Sectors EXT	EFh	10h	Enable use of SATA features et
44h	Zero EXT	EFh	10h 02h	Enable DMA Setup FIS Auto-Activate optimization
45h	Write Uncorrectable EXT	EFh	10h 03h	Enable Device-initiated interface power state (DIPM) transitions
47h	Read Log DMA EXT	EFh	10h 06h	Enable Software Settings Preservation (SSP)

Op Code		Description	Op Code			Description
57h		Write Log DMA EXT	EFh	10h	07h	Enable Device Automatic Partial to Slumber transitions
60h		Read FPDMA Queued	EFh	10h	09h	Enable Device Sleep
61h		Write FPDMA Queued	EFh	55h		Disable read look-ahead
70h-7Fh		Seek	EFh	66h		Disable reverting to power-on defaults
90h		Execute Device Diagnostic	EFh	82h		Disable volatile write cache
91h		Initialize Device Parameters	EFh	85h		Disable the APM feature set
92h		Download Microcode	EFh	90h		Disable use of SATA feature set
93h		Download Microcode DMA	EFh	90h	02h	Disable DMA Setup FIS Auto-Activate optimization
B0h		SMART	EFh	90h	03h	Disable Device-initiated interface power state (DIPM) transitions
B0h	D0h	SMART READ DATA	EFh	90h	06h	Disable Software Settings Preservation (SSP)
B0h	D1h	SMART READ ATTRIBUTE THRESHOLDS	EFh	90h	07h	Disable Device Automatic Partial to Slumber transitions
B0h	D2h	SMART ENABLE/DISABLE ATTRIBUTE AUTOSAVE	EFh	90h	09h	Disable Device Sleep
B0h	D3h	SMART SAVE ATTRIBUTE VALUES	EFh	AAh		Enable read look-ahead
B0h	D4h	SMART EXECUTE OFF-LINE IMMEDIATE	EFh	CCh		Enable reverting to power-on defaults
B0h	D5h	SMART READ LOG	F1h			Security Set Password
B0h	D6h	SMART WRITE LOG	F2h			Security Unlock
B0h	D8h	SMART ENABLE OPERATIONS	F3h			Security Erase Prepare
B0h	D9h	SMART DISABLE OPERATIONS	F4h			Security Erase Unit
B0h	DAh	SMART RETURN STATUS	F5h			Security Freeze Lock

B0h	DBh	SMART ENABLE/DISABLE AUTOMATIC OFF-LINE	F6h		Security Disable Password
B1h		Device Configuration	F8h		Read Native Max Address
B4h		Sanitize	F9h		Set Max Address
C4h	Read Multiple		F9h	01h	SET MAX SET PASSWORD
C5h	Write Multiple		F9h	02h	SET MAXLOCK
C6h	Set Multiple Mode		F9h	03h	SET MAX UNLOCK
C8h	Read DMA		F9h	04h	SET MAX FREEZE LOCIC

6.2. Identify Device Data

The following table details the sector data returned by the IDENTIFY DEVICE command.

Table 6-2 List of Device Identification

Word	F: Fixed V: Variable X: Both	Default Value	Description
0	F	0040h	General configuration bit-significant information
1	X	*1	Obsolete – Number of logical cylinders
2	V	C837h	Specific configuration
3	X	0010h	Obsolete – Number of logical heads (16)
4-5	X	00000000h	Retired
6	X	003Fh	Obsolete – Number of logical sectors per logical track (63)
7-8	V	00000000h	Reserved for assignment by the Compact Flash Association
9	X	0000h	Retired
10-19	F	Varies	Serial number (20 ASCII characters)
20-21	X	0000h	Retired
22	X	0000h	Obsolete
23-26	F	Varies	Firmware revision (8 ASCII characters)
27-46	F	Varies	Model number
47	F	8010h	7:0- Maximum number of sectors transferred per interrupt on MULTIPLE commands
48	F	4000h	Trusted Computing feature set options (not support)
49	F	2F00h	Capabilities
50	F	4000h	Capabilities
51-52	X	000000000h	Obsolete
53	F	0007h	Words 88 and 70:64 valid
54	X	*1	Obsolete – Number of logical cylinders

55	X	0010h	Obsolete
56	X	003Fh	Obsolete
57-58	X	*2	Obsolete
59	F	0110h	Sanitize and Number of sectors transferred per interrupt on MULTIPLE commands
60-61	F	*3	Maximum number of sector (28bit LBA mode)
62	X	0000h	Obsolete
63	F	0407h	Multi-word DMA modes supported/selected
64	F	0003h	PIO modes supported
65	F	0078h	Minimum Multiword DMA transfer cycle time per word
66	F	0078h	Manufacturer's recommended Multiword DMA transfer cycle time
67	F	0078h	Minimum PIO transfer cycle time without flow control
68	F	0078h	Minimum PIO transfer cycle time with IORDY flow control
69	F	0100h	Additional Supported (support download microcode DMA)
70	F	0000h	Reserved
71-74	F	0000000000000000h	Reserved for the IDENTIFY PACKET DEVICE command
75	F	001Fh	Queue depth
76	F	670eh	Serial SATA capabilities
77	F	0084h	Serial ATA Additional Capabilities
78	F	014Ch	Serial ATA features supported
79	V	0040h	Serial ATA features enabled
80	F	07F8h	Major Version Number
81	F	0000h	Minor Version Number
82	F	346bh	Command set supported
83	F	7d09h	Command set supported
84	F	6063h	Command set/feature supported extension
85	V	3469h	Command set/feature enabled
86	V	bc01h	Command set/feature enabled
87	V	6063h	Command set/feature default
88	V	003Fh	Ultra DMA Modes
89	F	0001h	Time required for security erase unit completion
90	F	001Eh	Time required for Enhanced security erase completion
91	V	0000h	Current advanced power management value
92	V	FFFEh	Master Password Revision Code
93	F	0000h	Hardware reset result. For SATA devices, word 93 shall be set to the value 0000h.
94	V	0000h	Obsolete
95	F	0000h	Stream Minimum Request Size

Word	F: Fixed V: Variable X: Both	Default Value	Description
96	V	0000h	Streaming Transfer Time – DMA
97	V	0000h	Streaming Access Latency – DMA and PIO
98-99	F	0000h	Streaming Performance Granularity
100-103	V	*4	Maximum user LBA for 48 bit Address feature set
104	V	0000h	Streaming Transfer Time – PIO
105	F	0008h	Maximum number of 512-byte blocks per DATA SET MANAGEMENT command
106	F	4000h	Physical sector size/Logical sector size
107	F	0000h	Inter-seek delay for ISO-7779 acoustic testing in microseconds
108-111	F	0000000000000000h	World Wide Name
112-115	F	0000000000000000h	Reserved
116	V	0000h	Reserved
117-118	F	00000000h	Words per logical Sector
119	F	4014h	Supported settings
120	F	4014h	Command set/Feature Enabled/Supported
121-126	F	0h	Reserved
127	F	0h	Obsolete
128	V	0021h	Security status
129-140	X	0h	Vendor specific
141	X	0001h	Vendor specific
142-159	X	0h	Vendor specific
160	F	0h	Reserved for CFA
161-167	X	0h	Reserved for CFA
168	V	Varies	Device Nominal Form Factor
169	F	0001h	DATA SET MANAGEMENT command is supported
170-173	F	000000000000 000 0h	Additional Product Identifier
174-175	X	0h	Reserved
176-205	V	0h	Current media serial number
206	F	0h	SCT Command Transport
207-208	F	0h	Reserved
209	F	4000h	Alignment of logical blocks within a physical block
210-211	V	00000000h	Write-Read-Verify Sector Count Mode 3 (not supported)
212-213	F	00000000h	Write-Read-Verify Sector Count Mode 2 (not supported)

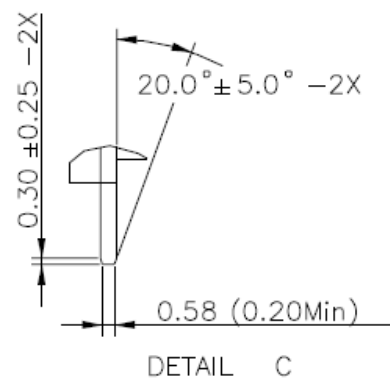
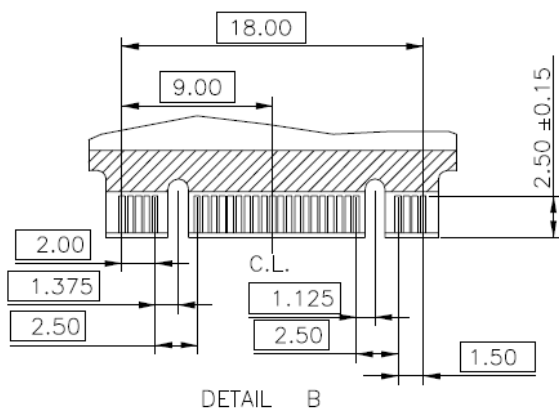
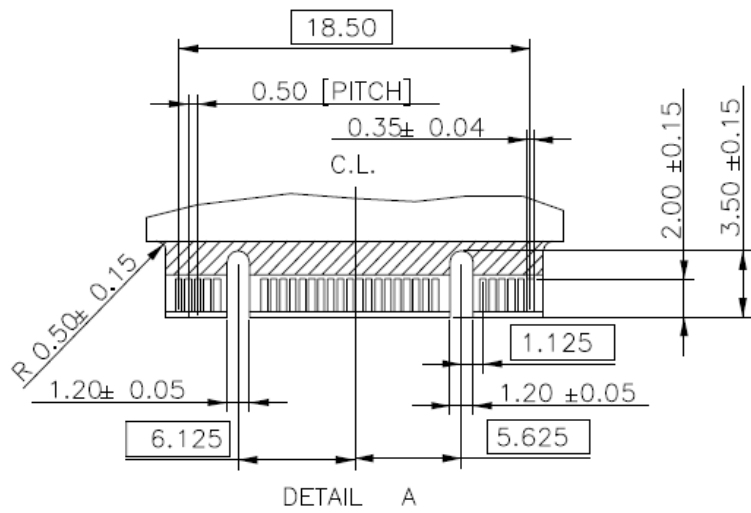
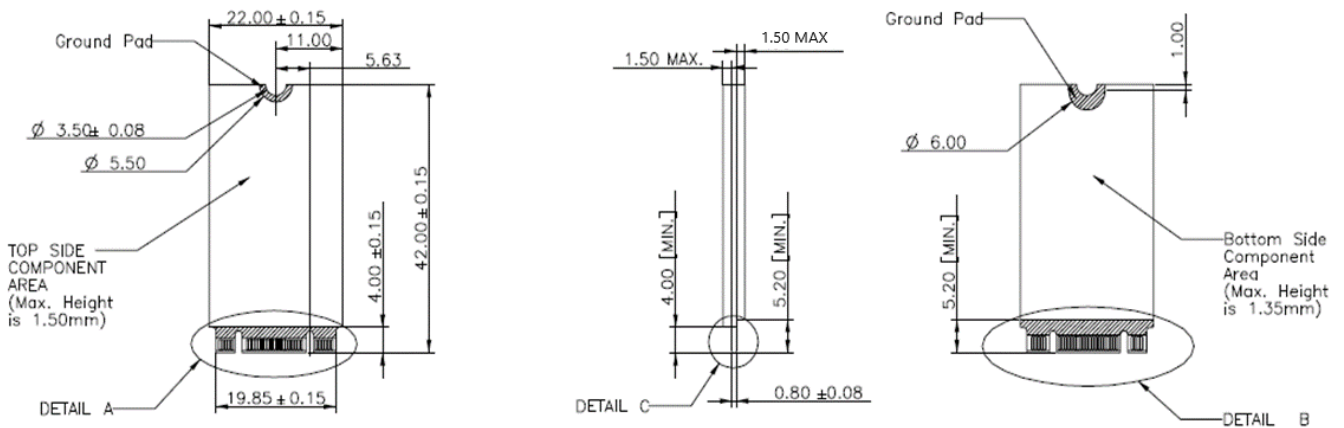
Word	F: Fixed V: Variable X: Both	Default Value	Description
214-216	X	0000h	Obsolete
217	F	0001h	Non-rotating media device
218	F	0000h	Reserved
219	F	0000h	NV Cache relate (not supported)
220	V	0000h	Write read verify feature set current mode
221	X	0000h	Reserved
222	F	107Fh	Transport major version number
223	F	0h	Transport minor version number
224-229	X	0h	Reserved
230-233	F	000000000000 0000h	Extend number of user addressable sectors
234	F	0001h	Minimum number of 512-byte data blocks per DOWNLOAD MICROCODE command for mode 03h
235	F	FFFEh	Maximum number of 512-byte data blocks per DOWNLOAD MICROCODE command for mode 03h
236-254	F	0h	Reserved
255	X	XXA5h XX is variable	Integrity word (Checksum and Signature)

Table 6-3 List of Device Identification for Each Capacity

Capacity (GB)	*1 (Word 1/Word 54)	*2 (Word 57 - 58)	*3 (Word 60 - 61)	*4 (Word 100 - 103)
16	3FFFh	FBFC10h	1DD40B0h	1DD40B0h
32	3FFFh	FBFC10h	3BA2EB0h	3BA2EB0h
64	3FFFh	FBFC10h	7740AB0h	7740AB0h
128	3FFFh	FBFC10h	EE7C2B0h	EE7C2B0h
256	3FFFh	FBFC10h	FFFFFFFFh	1DCF32B0h
512	3FFFh	FBFC10h	FFFFFFFFh	3B9E12B0h

7. PHYSICAL DIMENSIONS

Dimension: 42mm (L) x 22mm (W) x 3.8mm (H)



Unit : mm